

5.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

Features

- Guard Ring Die Construction for Transient Protection
- Ideally Suited for Automated Assembly
- Low Power Loss, High Efficiency
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application
- Lead Free Finish/RoHS Compliant (Note 1)

Mechanical Data

- Case: SMC
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: Cathode Band or Cathode Notch
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.21 grams (approximate)





Top View

Bottom View

Maximum Ratings @TA = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	B520C	B530C	B540C	B550C	B560C	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	30	40	50	60	V
RMS Reverse Voltage	V _{R(RMS)}	14	21	28	35	42	V
Average Rectified Output Current @ T _T = 90°C	l ₀			5.0			Α
Non-Repetitive Peak Forward Surge Current, 8.3 ms Single Half-Sine-Wave Superimposed on Rated Load	I _{FSM}			100			А

Thermal Characteristics

		T	1
Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Terminal	$R_{ hetaJT}$	10	°C/W
Thermal Resistance, Junction to Ambient (Note 2)	$R_{ hetaJA}$	50	°C/W
Operating Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

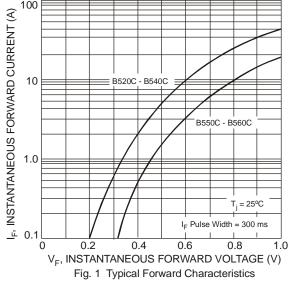
Electrical Characteristics @T_A = 25°C unless otherwise specified

Charac	cteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
Forward Voltage Drop	B520C, B530C, B540C	1 1/-	-	-	0.55	V	I _F = 5.0A, T _A = 25°C	
	B550C, B560C		-	-	0.70			
Lookaga Current (Note 2)				-	-	0.5	mA	@ Rated V _R , T _A = 25°C
Leakage Current (Note 3)		IR	-	-	20	IIIA	@ Rated V _R , T _A = 100°C	
Total Capacitance		C _T	-	Ī	300	pF	$V_R = 4V, f = 1MHz$	

Notes:

- 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.
- 2. Thermal Resistance: Junction to ambient, unit mounted on PC board with 8.0 mm² (0.033 mm thick) copper pads as heat sink.
- 3. Short duration pulse test used to minimize self-heating effect.





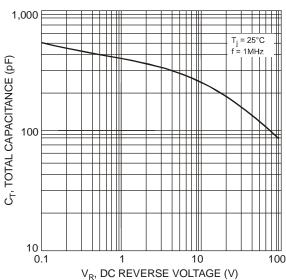


Fig. 3 Total Capacitance vs. Reverse Voltage

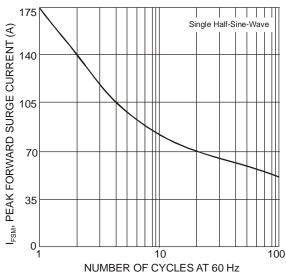
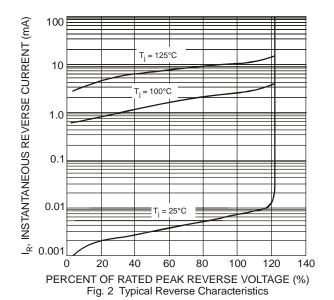
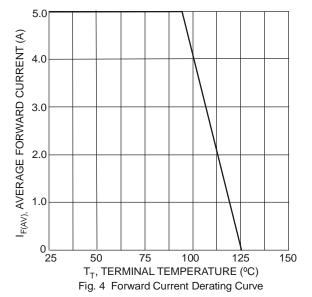


Fig. 5 Max Non-Repetitive Peak Forward Surge Current







Ordering Information (Note 4)

Part Number	Case	Packaging
B5xxC-13-F	SMC	3000/Tape & Reel

^{*} xx = Device type, e.g. B520C-13-F (SMC package).

Notes: 4. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



B5x0C = Product type marking code, ex: B540C (SMC package)

H = Manufacturers' code marking

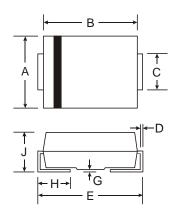
YWW = Date code marking

Y = Last digit of year (ex: 2 for 2002)

WW = Week code 01 to 52

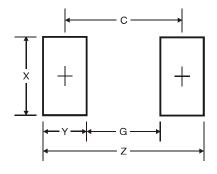
x = 2,3,4,5 or 6 - i.e., x = 4 for B540C

Package Outline Dimensions



SMC				
Dim	Min	Max		
Α	5.59	6.22		
В	6.60	7.11		
C	2.75	3.18		
D	0.15	0.31		
Е	7.75	8.13		
G	0.10	0.20		
Η	0.76	1.52		
7	2.00	2.62		
All Dimensions in mm				

Suggested Pad Layout



Dimensions	Value (in mm)
Z	9.3
G	4.4
Х	3.3
Y	2.5
С	6.8

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